CLAIMS

[Claim 1]

A manufacturing method of the adhesive film, the method comprising:

a step of preparing a laminated film including the base material layer (A), an adhesive resin layer (B) for temporarily fixing an electronic component on a first surface side of the base material layer (A), an adhesive resin layer (C) on a second surface side of the base material layer (A), and a separator (D) on a surface of the adhesive resin layer (B) opposite to the base material layer (A); and

a step of applying a marker on the separator (D) while slitting the laminated film to a predetermined size.

[Claim 2]

The manufacturing method of the adhesive film according to Claim 1, wherein the marker is positioned on a surface of the separator (D), and a thickness of the marker is equal to or more than 0.1 μm and equal to or less than 10 μm.

[Claim 3]

The manufacturing method of the adhesive film according to Claim 1 or 2, wherein the marker is linear.

[Claim 4]

The manufacturing method of the adhesive film according to

any one of Claims 1 to 3, wherein the adhesive resin layer (C) contains a heat-expansion type adhesive.

[Claim 5]

The manufacturing method of the adhesive film according to Claim 4, wherein the heat-expansion type adhesive is an adhesive whose adhesive strength is reduced or lost by heating at a temperature exceeding 100°C.

[Claim 6]

The manufacturing method of the adhesive film according to any one of Claims 1 to 5, wherein the adhesive film is wound on a winding core in a roll shape.

[Claim 7]

A manufacturing method of an electronic device, the method comprising a step of confirming that the separator (D) is peeled off from the adhesive film, based on a presence or absence of the marker in the adhesive film manufactured with the manufacturing method of the adhesive film according to any one of claims 1 to 6.

[Claim 8]

The manufacturing method of an electronic device according to Claim 7, further comprising a step of peeling the separator (D) constituting the adhesive film from the adhesive film before the step of confirming that the separator (D) is peeled off.

[Claim 9]

The manufacturing method of an electronic device according to Claim 7 or 8, further comprising, in this order:

a step of attaching a support substrate to the adhesive resin layer (C) of the adhesive film;

a step of placing an electronic component over the adhesive resin layer (B) of the adhesive film; and

a step of sealing the electronic component with a sealing material.

[Claim 10]

The manufacturing method of an electronic device according to Claim 9, wherein the sealing material includes an epoxy resin-based sealing material.

[Claim 11]

The manufacturing method of an electronic device according to any one of Claims 7 to 10, wherein the electronic device includes a fan-out type package.